

OptiMOS™ Power-MOSFET
Features

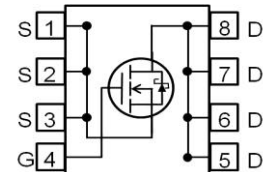
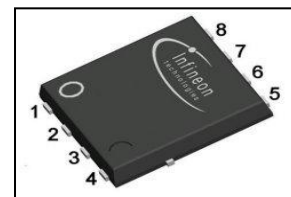
- Optimized for high performance Buck converter
- Monolithic integrated Schottky like diode
- Very low on-resistance $R_{DS(on)}$ @ $V_{GS}=4.5\text{ V}$
- 100% avalanche tested
- N-channel
- Qualified according to JEDEC¹⁾ for target applications
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21



Type	Package	Marking
BSC018NE2LSI	PG-TDSON-8	018NE2LI

Product Summary

V_{DS}	25	V
$R_{DS(on),max}$	1.8	mΩ
I_D	100	A
Q_{OSS}	23	nC
$Q_G(0V..10V)$	36	nC

PG-TDSON-8

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$V_{GS}=10\text{ V}, T_C=25\text{ °C}$	100	A
		$V_{GS}=10\text{ V}, T_C=100\text{ °C}$	97	
		$V_{GS}=4.5\text{ V}, T_C=25\text{ °C}$	100	
		$V_{GS}=4.5\text{ V}, T_C=100\text{ °C}$	84	
		$V_{GS}=10\text{ V}, T_A=25\text{ °C}, R_{thJA}=50\text{ K/W}^2)$	29	
Pulsed drain current ³⁾	$I_{D,pulse}$	$T_C=25\text{ °C}$	400	
Avalanche current, single pulse ⁴⁾	I_{AS}	$T_C=25\text{ °C}$	50	
Avalanche energy, single pulse	E_{AS}	$I_D=50\text{ A}, R_{GS}=25\text{ Ω}$	45	mJ
Gate source voltage	V_{GS}		±20	V

¹⁾ J-STD20 and JESD22

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Power dissipation	P_{tot}	$T_C=25\text{ °C}$	69	W
		$T_A=25\text{ °C}$, $R_{\text{thJA}}=50\text{ K/W}^2)$	2.5	
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	°C
IEC climatic category; DIN IEC 68-1			55/150/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - case	R_{thJC}		-	-	1.8	K/W
		top	-	-	20	
Device on PCB	R_{thJA}	6 cm ² cooling area ²⁾	-	-	50	

Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{ V}$, $I_{\text{D}}=10\text{ mA}$	25	-	-	V
Breakdown voltage temperature coefficient	$\frac{dV_{(\text{BR})\text{DSS}}}{dT_j}$	$I_{\text{D}}=10\text{ mA}$, referenced to 25 °C	-	15	-	mV/K
Gate threshold voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=250\text{ }\mu\text{A}$	1.2	-	2	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=20\text{ V}$, $V_{\text{GS}}=0\text{ V}$, $T_j=25\text{ °C}$	-	-	0.5	mA
		$V_{\text{DS}}=20\text{ V}$, $V_{\text{GS}}=0\text{ V}$, $T_j=125\text{ °C}$	-	2	-	
Gate-source leakage current	I_{GSS}	$V_{\text{GS}}=20\text{ V}$, $V_{\text{DS}}=0\text{ V}$	-	10	100	nA
Drain-source on-state resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=4.5\text{ V}$, $I_{\text{D}}=30\text{ A}$	-	1.9	2.4	mΩ
		$V_{\text{GS}}=10\text{ V}$, $I_{\text{D}}=30\text{ A}$	-	1.5	1.8	
Gate resistance	R_{G}		0.4	0.8	1.6	Ω
Transconductance	g_{fs}	$ V_{\text{DS}} >2 I_{\text{D}} R_{\text{DS(on)max}}$, $I_{\text{D}}=30\text{ A}$	65	130	-	S

³⁾ See figure 3 for more detailed information

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=12\text{ V}, f=1\text{ MHz}$	-	2500	3325	pF
Output capacitance	C_{oss}		-	1100	1463	
Reverse transfer capacitance	C_{rss}		-	110	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=12\text{ V}, V_{GS}=10\text{ V}, I_D=30\text{ A}, R_{G,ext}=1.6\ \Omega$	-	5.2	-	ns
Rise time	t_r		-	4.8	-	
Turn-off delay time	$t_{d(off)}$		-	24	-	
Fall time	t_f		-	3.6	-	

Gate Charge Characteristics⁵⁾

Gate to source charge	Q_{gs}	$V_{DD}=12\text{ V}, I_D=30\text{ A}, V_{GS}=0\text{ to }4.5\text{ V}$	-	6.3	8.4	nC
Gate charge at threshold	$Q_{g(th)}$		-	4.1	-	
Gate to drain charge	Q_{gd}		-	4.3	6.5	
Switching charge	Q_{sw}		-	6.6	-	
Gate charge total	Q_g		-	17	23	
Gate plateau voltage	$V_{plateau}$		-	2.5	-	V
Gate charge total	Q_g	$V_{DD}=12\text{ V}, I_D=30\text{ A}, V_{GS}=0\text{ to }10\text{ V}$	-	36	48	nC
Gate charge total, sync. FET	$Q_{g(sync)}$	$V_{DS}=0.1\text{ V}, V_{GS}=0\text{ to }4.5\text{ V}$	-	15	-	
Output charge	Q_{oss}	$V_{DD}=12\text{ V}, V_{GS}=0\text{ V}$	-	23	31	

Reverse Diode

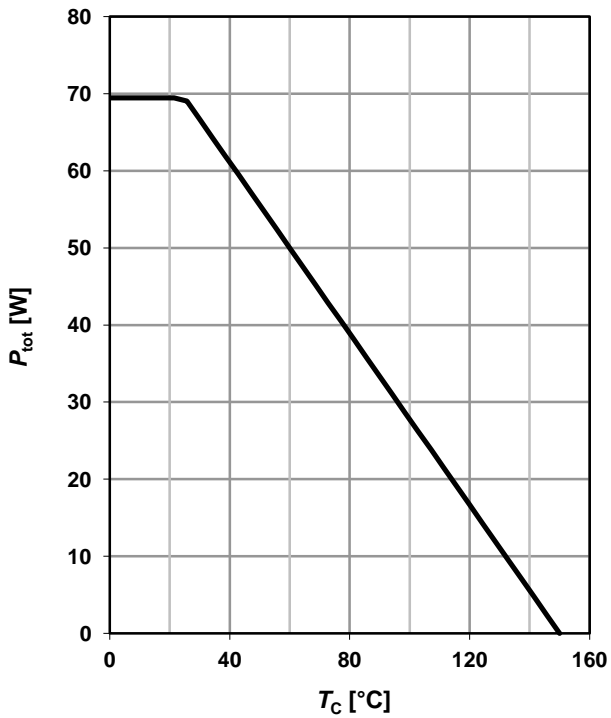
Diode continuous forward current	I_S	$T_C=25\text{ }^\circ\text{C}$	-	-	69	A
Diode pulse current	$I_{S,pulse}$		-	-	276	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=7\text{ A}, T_j=25\text{ }^\circ\text{C}$	-	0.55	-	V
Reverse recovery charge	Q_{rr}	$V_R=15\text{ V}, I_F=7\text{ A}, di_F/dt=400\text{ A}/\mu\text{s}$	-	5	-	nC

⁴⁾ See figure 13 for more detailed information

⁵⁾ See figure 16 for gate charge parameter definition

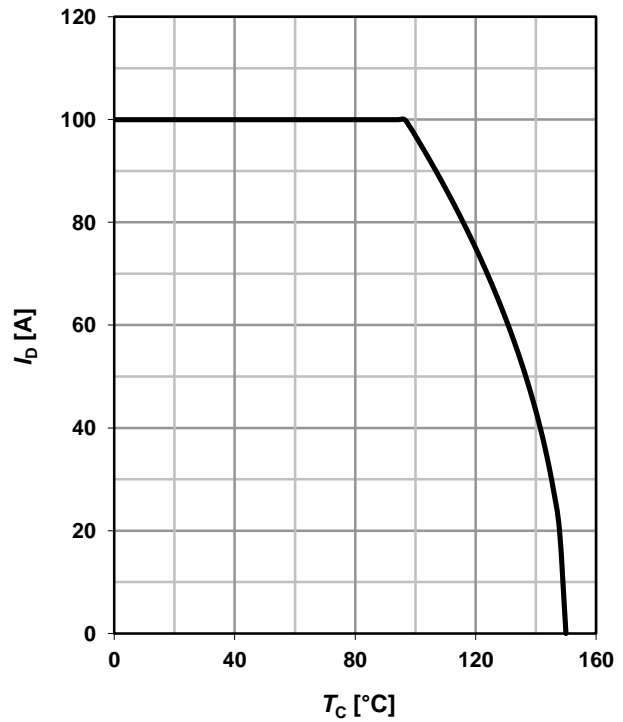
1 Power dissipation

$P_{tot}=f(T_C)$



2 Drain current

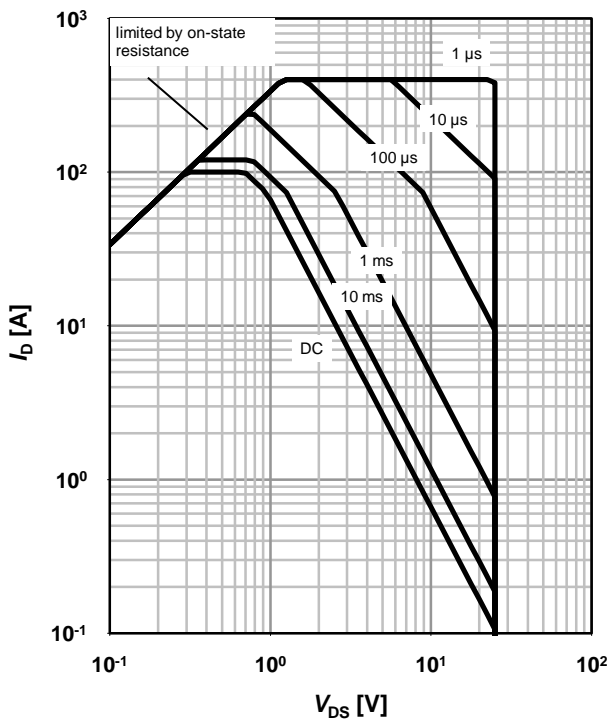
$I_D=f(T_C); V_{GS} \geq 10\text{ V}$



3 Safe operating area

$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0$

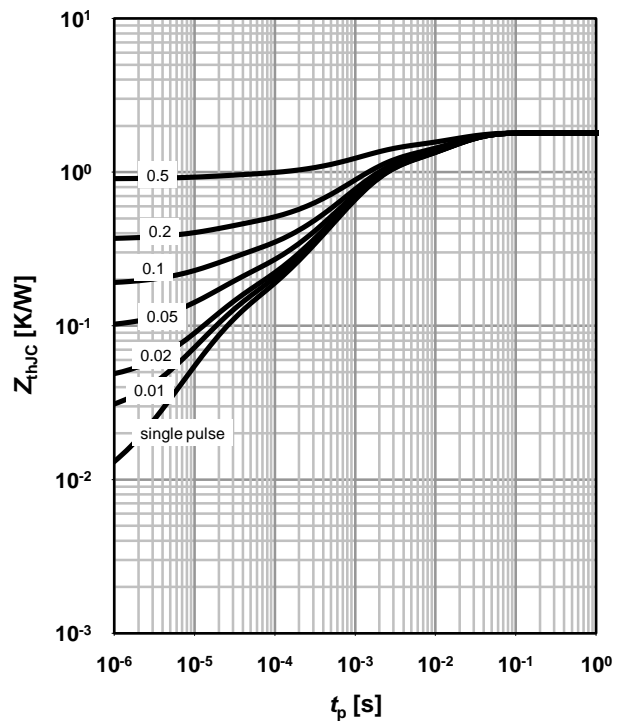
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC}=f(t_p)$

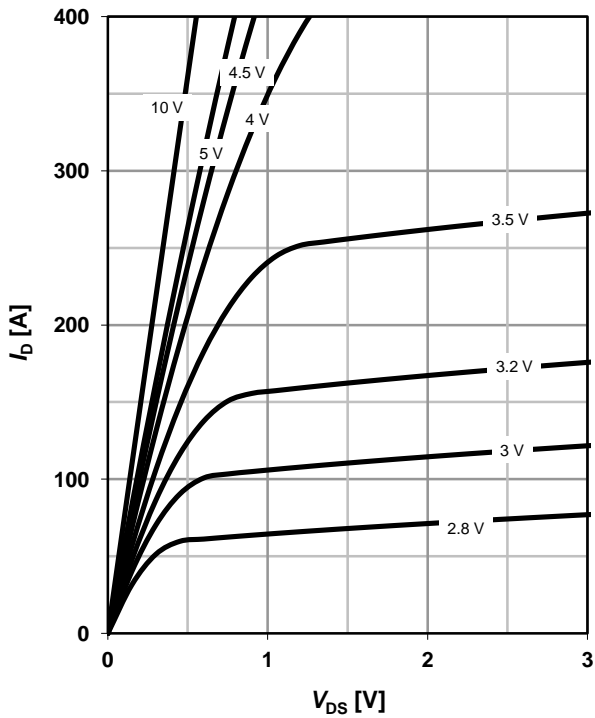
parameter: $D=t_p/T$



5 Typ. output characteristics

$I_D=f(V_{DS}); T_j=25\text{ °C}$

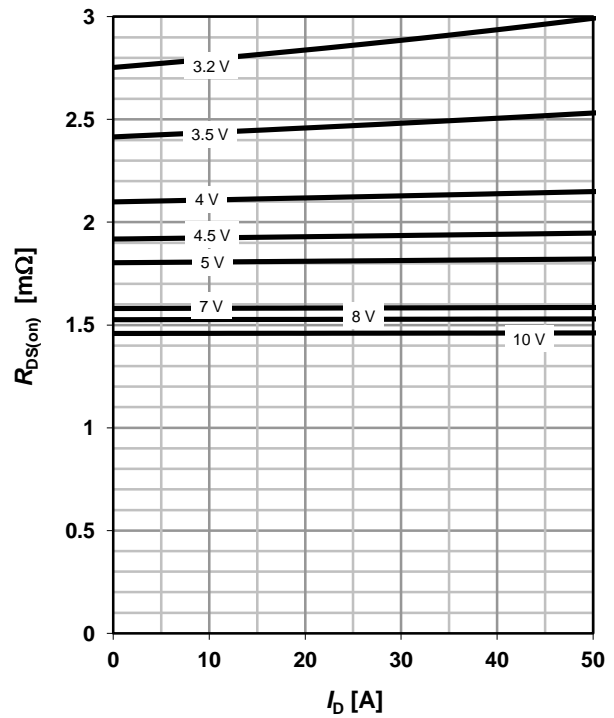
parameter: V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)}=f(I_D); T_j=25\text{ °C}$

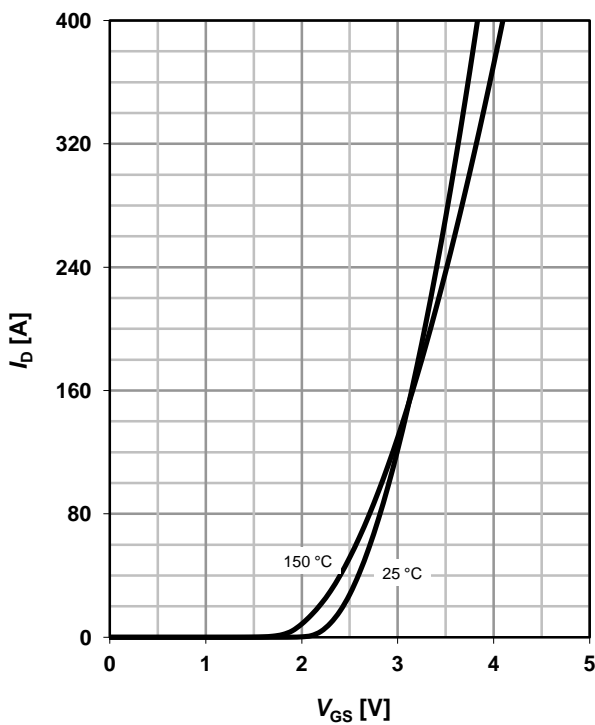
parameter: V_{GS}



7 Typ. transfer characteristics

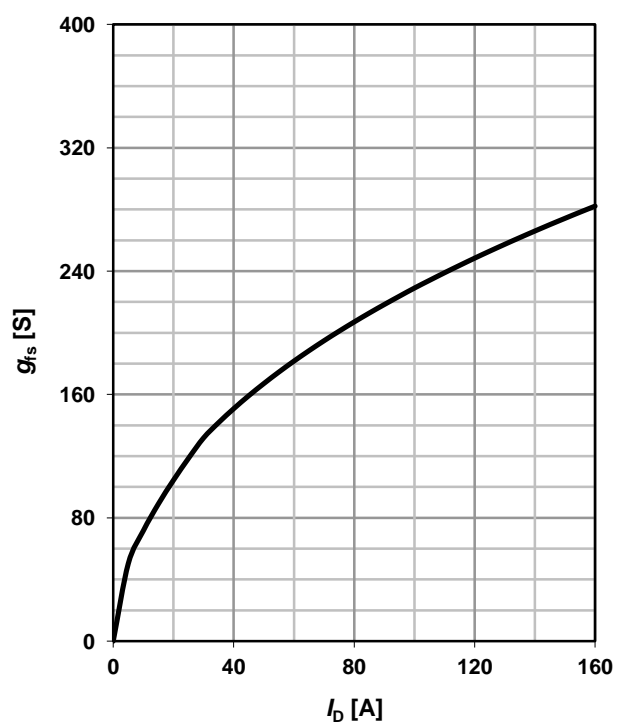
$I_D=f(V_{GS}); |V_{DS}|>2|I_D|R_{DS(on)max}$

parameter: T_j



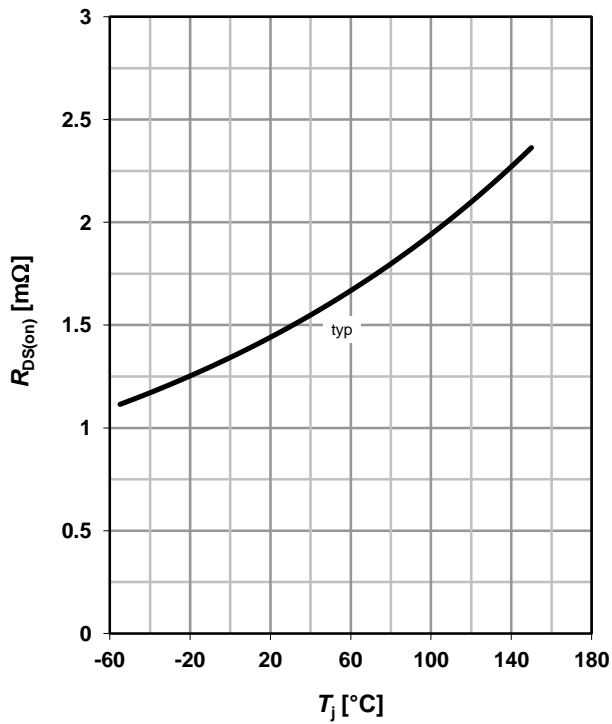
8 Typ. forward transconductance

$g_{fs}=f(I_D); T_j=25\text{ °C}$



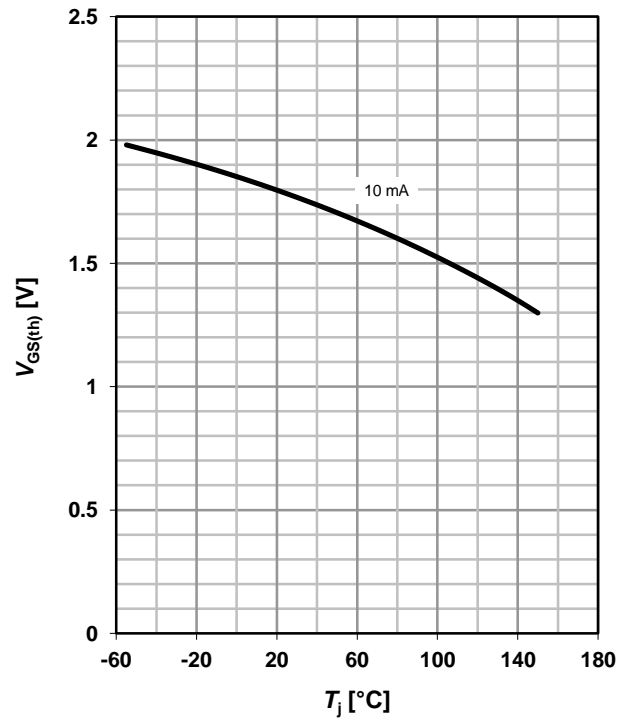
9 Drain-source on-state resistance

$R_{DS(on)}=f(T_j); I_D=30\text{ A}; V_{GS}=10\text{ V}$



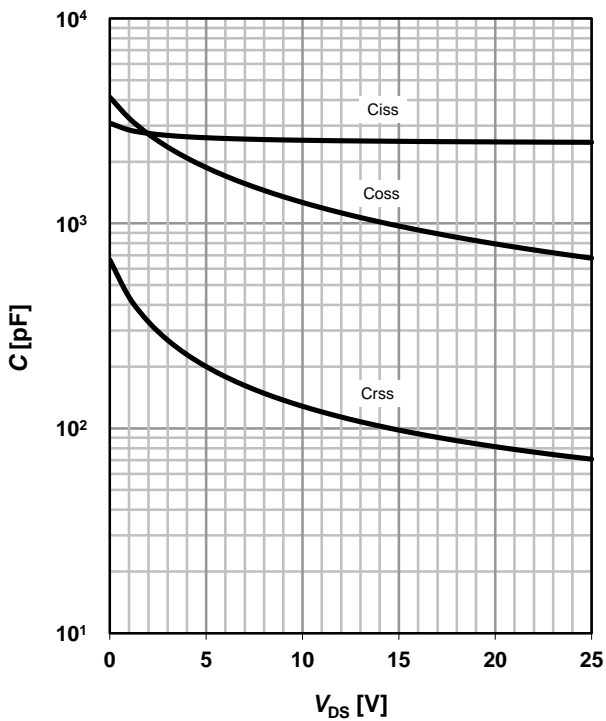
10 Typ. gate threshold voltage

$V_{GS(th)}=f(T_j); V_{GS}=V_{DS}; I_D=10\text{ mA}$



11 Typ. capacitances

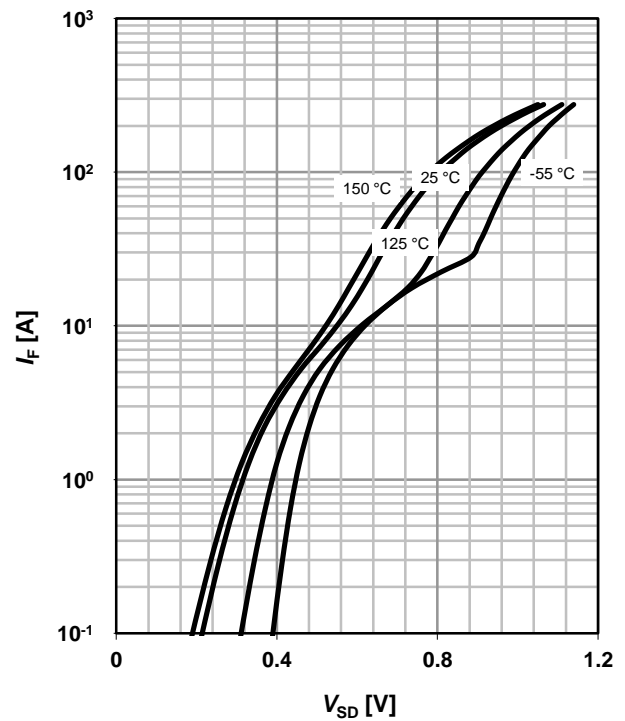
$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$



12 Forward characteristics of reverse diode

$I_F=f(V_{SD})$

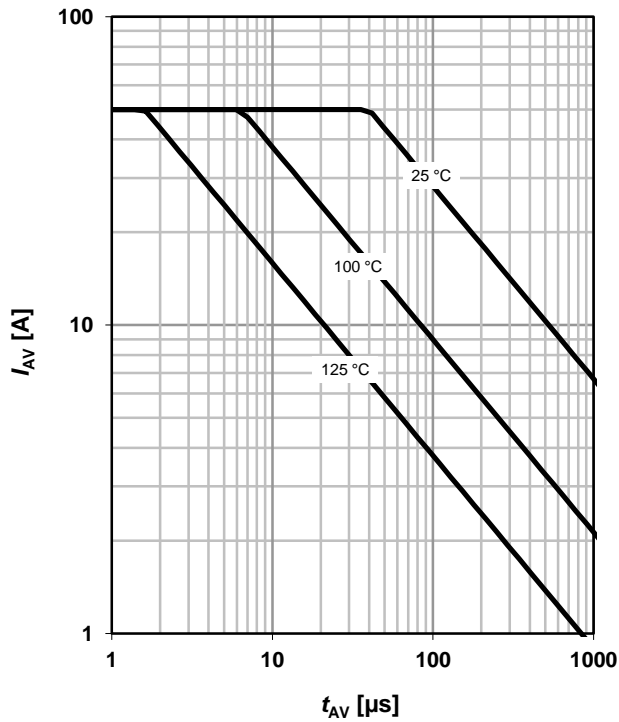
parameter: T_j



13 Avalanche characteristics

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

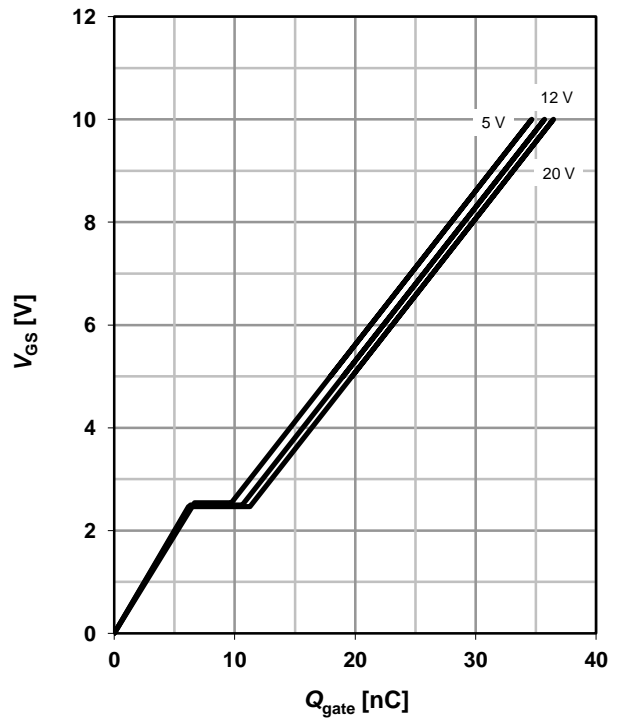
parameter: $T_{j(start)}$



14 Typ. gate charge

$V_{GS}=f(Q_{gate}); I_D=30 \text{ A pulsed}$

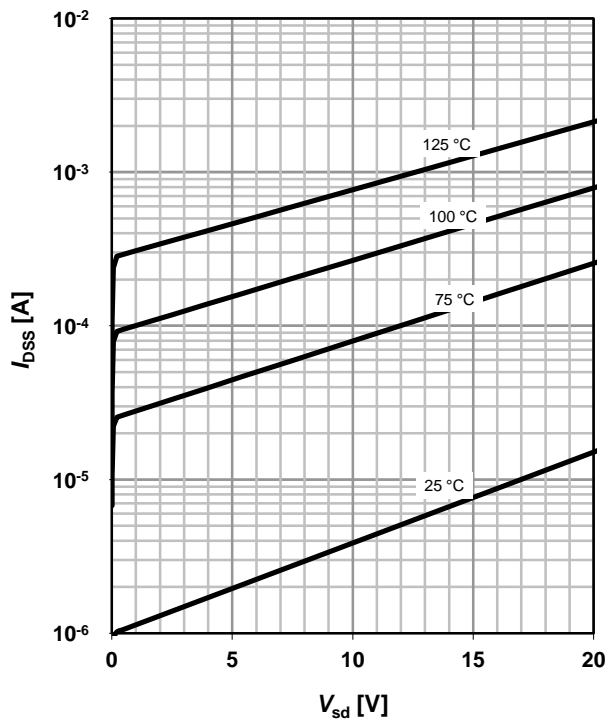
parameter: V_{DD}



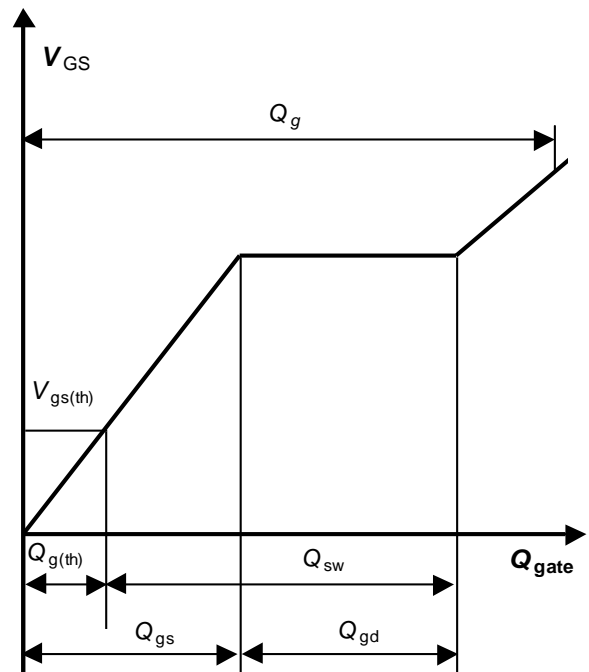
15 Typ. drain-source leakage current

$I_{DSS}=f(V_{DS}); V_{GS}=0 \text{ V}$

parameter: T_j



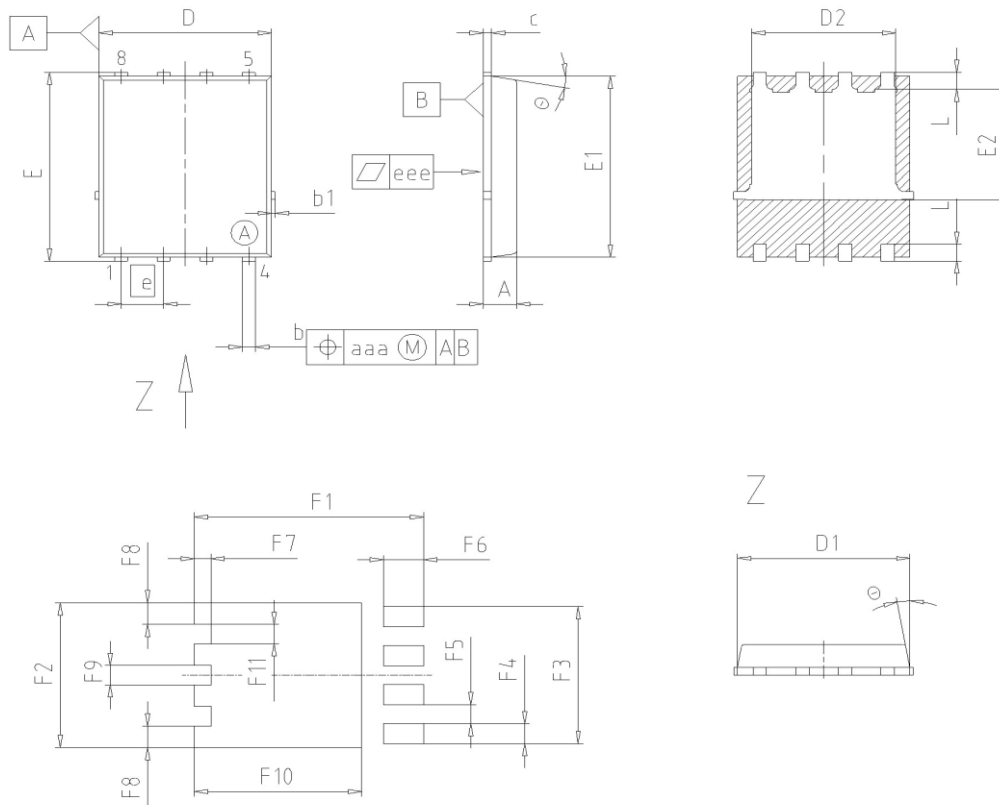
16 Gate charge waveforms



Package Outline

PG-TDSON-8

PG-TDSON-8: Outline



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.10	0.035	0.043
b	0.34	0.54	0.013	0.021
b1	0.02	0.22	0.001	0.008
c	0.15	0.35	0.006	0.014
D=D1	4.95	5.35	0.195	0.211
D2	4.20	4.40	0.165	0.173
E	5.95	6.35	0.234	0.250
E1	5.70	6.10	0.224	0.240
E2	3.40	3.80	0.134	0.150
e	1.27		0.050	
N	8		8	
L	0.45	0.65	0.018	0.026
□	8.5°	11.5°	8.5°	11.5°
aaa	0.25		0.010	
eee	0.05		0.002	
F1	6.75	6.95	0.266	0.274
F2	4.60	4.80	0.181	0.189
F3	4.36	4.56	0.172	0.180
F4	0.55	0.75	0.022	0.030
F5	0.52	0.72	0.020	0.028
F6	1.10	1.30	0.043	0.051
F7	0.40	0.60	0.016	0.024
F8	0.60	0.80	0.024	0.031
F9	0.53	0.73	0.021	0.029
F10	4.90	5.10	0.193	0.201
F11	0.53	0.73	0.021	0.029

DOCUMENT NO.
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SCALE

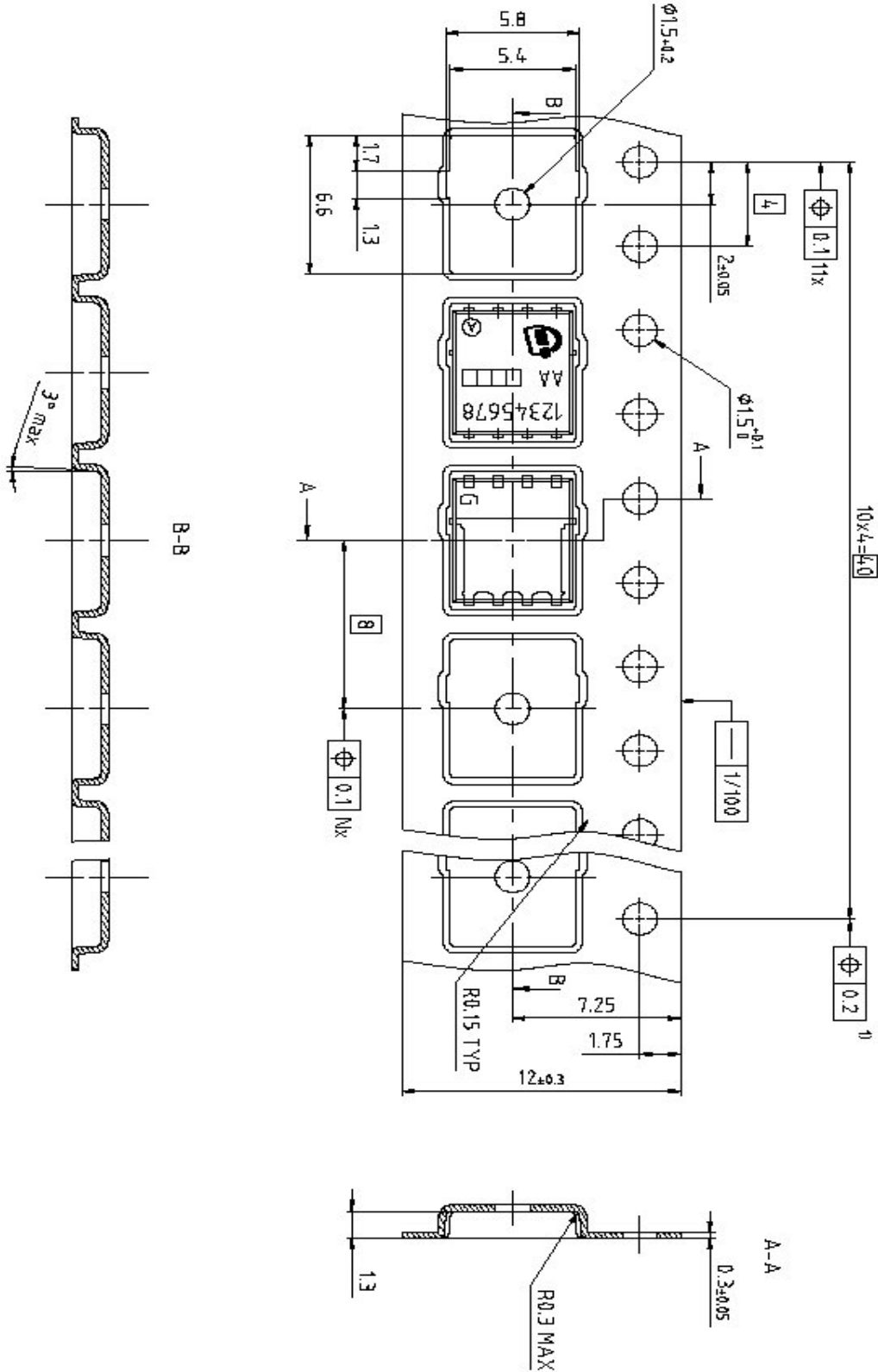
EUROPEAN PROJECTION

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REVISION
03

Package Outline

PG-TDSON-8: Tape



Dimensions in mm

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